

**APPLICATION**

**FOR**

**UNITED STATES LETTERS PATENT**

**TITLE:**           **USING EXTERNAL RADIATORS WITH  
ELECTROOSMOTIC PUMPS FOR  
COOLING INTEGRATED CIRCUITS**

**INVENTORS:**   **Sarah E. Kim, R. Scott List,  
James G. Maveety, Alan M. Myers,  
Quat T. Vu, Ravi Prasher, Ravi  
Mahajan, and Gilroy Vandentop**

Express Mail No. EL 990 136 848 US

Date: October 31, 2003

USING EXTERNAL RADIATORS WITH ELECTROSMOTIC  
PUMPS FOR COOLING INTEGRATED CIRCUITS

Background

This invention relates generally to cooling integrated circuits.

Electroosmotic pumps use electric fields to pump a  
5 fluid. In one application, they may be fabricated using semiconductor fabrication techniques. They then may be applied to the cooling of integrated circuits, such as microprocessors.

For example, an integrated circuit electroosmotic pump  
10 may be operated as a separate unit to cool an integrated circuit. Alternatively, the electroosmotic pump may be formed integrally with the integrated circuit to be cooled. Because the electroosmotic pumps, fabricated in silicon, have an extremely small form factor, they may be effective  
15 at cooling relatively small devices, such as semiconductor integrated circuits.

Thus, there is a need for better ways of cooling integrated circuits.

Brief Description of the Drawings

20 Figure 1 is a schematic depiction of the operation of the embodiment in accordance with one embodiment of the present invention;

Figure 2 is an enlarged cross-sectional view of one embodiment of the present invention at an early stage of manufacture;

5 Figure 3 is an enlarged cross-sectional view at a subsequent stage of manufacture in accordance with one embodiment of the present invention;

Figure 4 is an enlarged cross-sectional view at a subsequent stage of manufacture in accordance with one embodiment of the present invention;

10 Figure 5 is an enlarged cross-sectional view at a subsequent stage of manufacture in accordance with one embodiment of the present invention;

Figure 6 is an enlarged cross-sectional view at a subsequent stage of manufacture in accordance with one embodiment of the present invention;

15 Figure 7 is an enlarged cross-sectional view taken along the lines 7-7 in Figure 8 at a subsequent stage of manufacture in accordance with one embodiment of the present invention;

20 Figure 8 is a top plan view of the embodiment shown in Figure 8 in accordance with one embodiment of the present invention;

Figure 9 is an enlarged cross-sectional view of a completed structure in accordance with one embodiment of the present invention;

Figure 10 is a depiction of a recombiner at an early stage of manufacture;

Figure 11 is an enlarged cross-sectional view at a subsequent stage of manufacture in accordance with one  
5 embodiment of the present invention;

Figure 12 is an enlarged top plan view at a subsequent stage of manufacture in accordance with one embodiment of the present invention;

Figure 13 is a cross-sectional view taken general  
10 along the line 13-13 in Figure 12 in accordance with one embodiment of the present invention;

Figure 14 is an enlarged cross-sectional view at a subsequent stage of manufacture in accordance with one embodiment of the present invention;

15 Figure 15 is a top plan view of the embodiment shown in Figure 14 at a subsequent stage of manufacture in accordance with one embodiment of the present invention;

Figure 16 is a cross-sectional view taken generally along the line 16-16 in Figure 15 in accordance with one  
20 embodiment of the present invention;

Figure 17 is a cross-sectional view corresponding to Figure 16 at a subsequent stage of manufacture in accordance with one embodiment of the present invention;

Figure 17A is a side-elevational view of a re-combiner  
25 in accordance with one embodiment of the present invention;

Figure 18 is a schematic view of a packaged system in accordance with one embodiment of the present invention;

Figure 19 is a cross-sectional view of a packaged system in accordance with another embodiment of the present invention;

Figure 20 is a cross-sectional view of a packaged system in accordance with another embodiment of the present invention;

Figure 21 is a schematic view of a cooling system in accordance with another embodiment of the present invention;

Figure 22 is a schematic view of still another embodiment of the present invention;

Figure 23 is a schematic view of still another embodiment of the present invention;

Figure 24 is an enlarged, cross-sectional view through one embodiment of the present invention taken generally along the line 24-24 in Figure 25; and

Figure 25 is a cross-sectional view taken generally along the line 25-25 in Figure 24 in accordance with one embodiment of the present invention.

#### Detailed Description

Referring to Figure 1, an electroosmotic pump 28 fabricated in silicon is capable of pumping a fluid, such as a cooling fluid, through a frit 18. The frit 18 may be coupled on opposed ends to electrodes 29 that generate an

electric field that results in the transport of a liquid through the frit 18. This process is known as the Electroosmotic effect. The liquid may be, for example, water and the frit may be composed of silicon dioxide in one embodiment. In this case hydrogen from hydroxyl groups on the wall of the frit deprotonate resulting in an excess of protons moving transversely to the wall or transversely to the direction of fluid movement, indicated by the arrows A. The hydrogen ions move in response to the electric field applied by the electrodes 29 in the direction of the arrows A. The non-charged water atoms also move in response to the applied electric field because of drag forces that exist between the ions and the water atoms.

As a result, a pumping effect may be achieved without any moving parts. In addition, the structure may be fabricated in silicon at extremely small sizes making such devices applicable as pumps for cooling integrated circuits.

In accordance with one embodiment of the present invention, the frit 18 may be made of an open and connected cell dielectric thin film having open nanopores. By the term "nanopores," it is intended to refer to films having pores on the order of 10 to 1000 nanometers. In one embodiment, the open cell porosity may be introduced using the sol-gel process. In this embodiment, the open cell porosity may be introduced by burning out the porogen

phase. However, any process that forms a dielectric film having interconnected or open pores on the order of 10 to 1000 nanometers may be suitable in some embodiments of the present invention.

5       For example, suitable materials may be formed of organosilicate resins, chemically induced phase separation, and sol-gels, to mention a few examples. Commercially available sources of such products are available from a large number of manufacturers who provide those films for  
10 extremely low dielectric constant dielectric film semiconductor applications.

      In one embodiment, an open cell xerogel can be fabricated with 20 nanometer open pore geometries that increase maximum pumping pressure by a few orders of  
15 magnitude. The xerogel may be formed with a less polar solvent such as ethanol to avoid any issues of water tension attacking the xerogel. Also, the pump may be primed with a gradual mix of hexamethyldisilazane (HMDS), ethanol and water to reduce the surface tension forces.  
20 Once the pump is in operation with water, there may be no net forces on the pump sidewalls due to surface tension.

      Referring to Figures 2-9, the fabrication of an integrated electroosmotic pump 28 using a nanoporous open cell dielectric frit 18 begins by patterning and etching to  
25 define an electroosmotic trench.

Referring to Figure 2, a thin dielectric layer 16 may be grown over the trench in one embodiment. Alternatively, a thin etch or polish-stop layer 16, such as a silicon nitride, may be formed by chemical vapor deposition. Other techniques may also be used to form the thin dielectric layer 16. The nanoporous dielectric layer 18 may then be formed, for example, by spin-on deposition. In one embodiment, the dielectric layer 18 may be in the form of a sol-gel. The deposited dielectric layer 18 may be allowed to cure.

Then, referring to Figure 3, the structure of Figure 2 may be polished or etched back to the stop layer 16. As a result, a nanoporous dielectric frit 18 may be defined within the layer 16, filling the substrate trench.

Referring next to Figure 4, openings 24 may be defined in a resist layer 22 in one embodiment of the present invention. The openings 24 may be effective to enable electrical connections to be formed to the ends of the frit 18. Thus, the openings 24 may be formed down to a deposited oxide layer 20 that may encapsulate the underlying frit 18. In some embodiments, the deposited oxide layer 20 may not be needed.

The resist 22 is patterned as shown in Figure 4, the exposed areas are etched and then used as a mask to form the trenches 26 alongside the nanoporous dielectric layer 18 as shown in Figure 5. Once the trenches 26 have been



formed, a metal 29 may be deposited on top of the wafer. In one embodiment, sputtering can be used to deposit the metal. The metal 29 can be removed by etching or lift-off techniques in such a manner as to leave metal only in the trench at the bottom of the trenches 26 as shown in Figure 6. The metal 29 is advantageously made as thin as possible to avoid occluding liquid access to the exposed edge regions of the frit 18, which will ultimately act as the entrance and exit openings to the pump 28. The metal 29 may be thick enough, however, to assure adequate current flow without damage to the electrodes. Additionally, it is advantageous if the metal 29 also is deposited along the edges of the frit to a thickness which does not block the pore openings. This assures a uniform electric field along the entire depth of the frit.

Referring to Figure 7, a chemical vapor deposition material 34 may be formed over the frit 18 and may be patterned with photoresist and etched, as indicated at 32, to provide for the formation of channels 38 shown in Figure 8. The channels 38 are etched through the deposited material 34 over the substrate 40. The channels 38 act as conduits to convey liquid to and from the rest of the pump 41. Also, electrical interconnections 36 may be fabricated by depositing metal (for example by sputtering), and removing the metal in selected areas (for example by lithographic patterning and etching across the wafer to

enable electrical current to be supplied to the electrodes 29. This current sets up an electric field that is used to draw the fluid through the pump 28.

Referring to Figure 9, the fluid may pass through the microchannels 38 and enter the frit 18 by passing over the first electrode 29. The fluid is drawn through the frit 18 by the electric field and the disassociation process described previously. As a result, the fluid, which may be water, is pumped through the pump 28.

Referring now to Figures 10 through 17, one embodiment of a fabrication technique for making an integrated recombiner is illustrated. Initially, a semiconductor substrate 60, such as a silicon wafer, may have a trench 62 formed therein by patterning and etching techniques, for example. Thereafter, a catalyst material 64, such as platinum, is sputter deposited as shown in Figure 10. The catalyst material 64 is polished off the top of the wafer substrate 60 so only the portion 66 remains as shown in Figure 11. A resist may be spun-on and patterned to form microchannels 68a and 68b, shown in Figures 12 and 13.

The microchannels 68a and 68b may be etched to the depth of the top of the catalyst material 66 and the resist used to do the etching may be cleaned. Then a resist 70 may be spun-on and ashed to clear the top of the wafer substrate 60, as shown in Figure 14. A barrier, such as TiTiN, and copper 72 may be sputtered on top of the wafer

substrate 60. A resist lift off may be used to remove the copper from the top of the catalyst material 66 and the microchannels 68a and 68b as shown in Figure 17.

5 A porous Teflon layer (not shown) may be deposited over the wafer surface and either etched back or polished so that the Teflon covers the catalyst material 66 while having the copper 72 exposed. The Teflon layer protects the catalyst material 66 from getting wet when re-combined gas turns into water.

10 A pair of identical substrates 60, processed as described above, may then be combined in face-to-face abutment to form a re-combiner 30 as shown in Figure 17A. The substrates 60 may be joined by copper-to-copper bonding where there is no trench 16 or channel 68. Other bonding  
15 techniques, such as eutectic or direct bonding, may also be used to join the two wafers together. The trenches 16 and channels 68 may be aligned to form a passage for cooling fluid circulation over the catalyst material 66.

The re-combiner 30 may be used to reduce the buildup  
20 of gas in the cooling fluid pumped by the pump 28. Exposure of the gases to catalytic material 66 results in gas recombination. The re-combiner 30 may be made deep enough to avoid being covered with water formed from recombined gas and the cooling fluid itself.

25 Electroosmotic pumps 28 may be provided in a system 100 coupled by fluid passageways as indicated in Figure 18.

The passageways couple a radiator 132, a re-combiner 30, and a set of microchannels 116 in a circuit or pathway for fluid. Thus, the fluid pumped by the pump 28 passes through the channel 116 and the re-combiner 30 to the  
5 radiator 132 where heat is removed to the surrounding environment. Thus, the microchannels 116, associated with an integrated circuit not shown in Figure 18, provide cooling for that integrated circuit.

Referring to Figure 19, a surface mount or flip-chip  
10 package 129 may support an integrated circuit 124 having bump connections 126 to the package 129. The top side of the integrated circuit 124 faces towards the package 129.

The die 114 active semiconductor 124 is underneath the bulk silicon 122. The die 114 may be coupled to another  
15 die 112 by a copper-to-copper connection 120. That is, copper metal 120 on each die 112 and 114 may be fused to connect the dice 112 and 114. The die 112 may be bonded by glass, polymers, or dielectric bonding to the die 140.

The die 112 may include a dielectric layer 118 and a  
20 plurality of microchannels 116, which circulate cooling fluid. On the opposite side of the die 112 are a plurality of electroosmotic pumps 28 formed as described previously. A dielectric layer 136 couples the die 112 to a die 140, which forms the re-combiner 30. The re-combiner/condenser  
25 30 may be coupled to an external radiator 132 such as a finned heat exchanger.

The external radiator 132 may be spaced from the rest of the system atop tubes 133 that enable fluid to be circulated through the body of the radiator 132. The use of an external radiator 132 enables the removal of more  
5 heat.

Exterior edges of the stack 110 may be sealed except for edge areas needed to provide fluid inflow and egress of the microchannels 116.

Thus, fluid may be circulated by the pumps 28 through  
10 the microchannels 116 to cool the die 114 active semiconductor 124. That fluid may be passed upwardly through appropriate passageways in the die 112 to the electroosmotic pumps 28. A pump liquid may then be communicated by appropriate passageways to the re-  
15 combiner/condenser 30.

In some embodiments, by providing a vertical stack 110 of three dice, a compact footprint may be achieved in a conventional package 129. The re-combiner 30 may be thermally insulated by the dielectric layer 136 from the  
20 lower, heat producing components.

Referring to Figure 20, the structure shown therein corresponds in most respects to the structure shown in Figure 19. The only difference is that the copper-to-copper bonding is eliminated. In this case, a glass,  
25 polymer, or dielectric bond process may be utilized to

connect the dice 112 and 114, as well as the dice 112 and 140.

Referring to Figure 21, a bumpless build-up layer (BBUL) package 142 is illustrated. The package 142 has  
5 build-up layers because the package is "grown" (built up) around the silicon die, rather than being manufactured separately and bonded to it. Bumpless build-up layer packaging is similar to flip-chip packaging except that no  
10 the package. The build-up layers 144 provide multiple metal interconnection layers that enable electrical connections between the package pins and contacts on the dice 112 and 114 without the need for bumps.

The dice 112 and 114 are separately fabricated and, in  
15 this case, are bonded by a copper/copper bond as illustrated. The re-combiner 30 is inserted in the BBUL package 142 separately from the stack of the dice 112 and 114. Build-up layers 144 may be provided between the BBUL package 142 and the radiator 132 and on the bottom of the  
20 package 142. The build-up layers 144 serve to couple the re-combiner 30 to the stack including the dice 112 and 114. Channels may be built unto the layers 144 to couple fluid from pumps 28 and microchannels 116 to the recombiner 30 and from the recombiner 30 to the radiator 132.

25 Referring to Figure 22, the structure therein corresponds to the structure shown in Figure 21 but, again,

the copper-to-copper bonding between the dice 112 and 114 is replaced with either polymer, dielectric, or glass bonding processes.

Referring next to Figure 23, a BBUL package 142  
5 corresponds to the embodiment shown in Figure 21, except that the dice 112 and 114 are not stacked. A build-up layer 144 couples the die 112 to the die 116 and the re-combiner 30.

Via channels may be used to couple the dice 112, 114,  
10 and 140. Alternatively, channels or tubes may be utilized for this purpose. The channels or tubes may be formed in the same structure or may be separate structures physically joined to the dies 112, 114, and 140 for this purpose.

As another example, referring to Figure 24, a package  
15 156 may have a first trench 154 and a second trench 160 which are isolated from one another. Interior edges of the trenches 154, 160 are defined by the die 114 which is inserted into the package 156. The trenches 154 and 160 may communicate with ports 158 and 162 which allow fluid to  
20 be added or exhausted from the package exterior. The edges of the die 114 are in communication with the fluid filled trench 154. Fluid from the fluid filled trench 154 may enter the stack 110 and may leave through the fluid filled trench 160. Fluid may be recirculated by tubing 168 which  
25 connects the ports 162 and 158. A radiator 132 may be coupled by the tubing 168.

Referring to Figure 25, the fluid filled trench 154 may fluidically communicate with one or more microchannels 122, that in turn communicate with one or more electroosmotic pumps 28 and re-combiners 30. In this way, fluid may be pumped by the electroosmotic pump 28 for selective cooling of hot areas of the die 114. Upper and lower covers 164 and 166 may be included on the package in one embodiment of the present invention.

While the present invention has been described with respect to a limited number of embodiments, those skilled in the art will appreciate numerous modifications and variations therefrom. It is intended that the appended claims cover all such modifications and variations as fall within the true spirit and scope of this present invention.

What is claimed is: